



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20260223009.1**  
**Add Cu as Alternative Wire Base Metal for Selected Device(s)**  
**Change Notification / Sample Request**

**Date:** February 24, 2026  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20260223009.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
ADS1292RIRSMT	ADS1292RIRSMT
ADS1120IRVAR	ADS1120IRVAR
OPA2172IDRGT	OPA2172IDRGT
OPA2316IDRGT	OPA2316IDRGT
ADS1220IRVAR	NULL
ADS8920BRGET	ADS8920BRGET
ADS8681IRUMR	NULL
ADS8924BRGET	ADS8924BRGET
OPA2316IDRGR	NULL
ADS8681WRUMT	NULL
INA188IDRJR	INA188IDRJR
ADS8681IRUMT	ADS8681IRUMT
ADS8900BRGET	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20260223009.1			<b>PCN Date:</b>	February 24, 2026								
<b>Title:</b>	Add Cu as Alternative Wire Base Metal for Selected Device(s)												
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services									
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 25, 2026		<b>Estimated Sample Availability:</b>	April 25, 2026									
<b>*Sample requests received after April 25, 2026 will not be supported.</b>													
<b>Change Type:</b>													
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process								
<b>PCN Details</b>													
<b>Description of Change:</b>													
Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:													
<table border="1"> <thead> <tr> <th>Material</th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>0.96mil Au</td> <td>1.0mil Cu</td> </tr> </tbody> </table>						Material	Current	Proposed	Wire diam/type	0.96mil Au	1.0mil Cu		
Material	Current	Proposed											
Wire diam/type	0.96mil Au	1.0mil Cu											
<b>Reason for Change:</b>													
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock													
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>													
Review the SDP for full evaluation of the change based on the customer use case.													
<b>Impact on Environmental Ratings:</b>													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change			
RoHS	REACH	Green Status	IEC 62474										
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
<b>Changes to product identification resulting from this PCN:</b>													
None													
<b>Product Affected:</b>													
ADS1120IRVAR	ADS8681IRUMT	ADS8922BRGET											
ADS1120IRVAT	ADS8681WRUMT	ADS8924BRGER											
ADS1220IRVAR	ADS8900BRGER	ADS8924BRGET											
ADS1220IRVAT	ADS8900BRGET	AFE032IRGZR											
ADS1283AIRHFR	ADS8902BRGER	AFE032IRGZT											
ADS1283AIRHFT	ADS8902BRGET	INA188IDRJR											
ADS1283BIRHFR	ADS8904BRGER	OPA1688IDRGR											
ADS1283BIRHFT	ADS8904BRGET	OPA1688IDRGT											

ADS1283IRHFR	ADS8910BRGER	OPA2172IDRGR
ADS1283IRHFT	ADS8910BRGET	OPA2172IDRGT
ADS1284IRHFR	ADS8912BRGER	OPA2316IDRGR
ADS1284IRHFT	ADS8912BRGET	OPA2316IDRGT
ADS1287IRHFR	ADS8914BRGER	SN1602018RVFR
ADS1287IRHFT	ADS8914BRGET	SN1807012RVFR
ADS1292RIRSMR	ADS8920BRGER	TPS548B22RVFR
ADS1292RIRSMT	ADS8920BRGET	TPS548B22RVFT
ADS8681IRUMR	ADS8922BRGER	

## Qualification Report

Approve Date 24-January-2026

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AFE032IRGZR	Qual Device: ADS1283BIRHFR	Qual Device: OPA1678IDRGR	QBS Package Reference: BUF12840AIRGER	QBS Package Reference: INA223AIDSKR	QBS Package Reference: SN0903048DRG
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	1/77/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	1/77/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	1/77/0	-	-
BP	-	Bond Pull	-	-	3/228/0	3/228/0	3/228/0	-	-	-
BS	-	Bond Shear	-	-	3/228/0	3/228/0	3/228/0	-	-	-
FTY	-	Final Test Yield	-	-	3/Pass	3/Pass	3/Pass	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device AFE032IRGZR is qualified at MSL3 260C

Qual Device ADS1283BIRHFR is qualified at MSL3 260C

Qual Device OPA1678IDRGR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2501-047

# Qualification Report

Approve Date 13-JANUARY -2026

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN1602018RVFR	QBS Reference: TPS543B20RVFR	QBS Reference: TPS543C20ARVFT	QBS Reference: TPS546C20RVFR	QBS Reference: TPS548D22RVFR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass	Pass	Pass
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	1/1/0	1/1/0	1/1/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN1602018RVFR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2309-020

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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